

<b>K</b>	<b>4</b>	<b>R</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>-</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	<b>X</b>	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

## 1. Memory (K)

## 2. DRAM : 4

## 3. Small Classification

R : RDRAM®

## 4~5. Density, Refresh

27 : 128M, 16K/32ms (1.95us)  
 44 : 144M, 16K/32ms (1.95us)  
 57 : 256M, 16K/32ms (1.95us)  
 88 : 288M, 16K/32ms (1.95us)  
 52 : 512M, 32K/32ms (0.98us)  
 76 : 576M, 32K/32ms (0.98us)

## 6~7. Organization

16 : x16  
 18 : x18

## 8. Bank

6 : 32Bank

## 9. Interface, VDD, VDDQ

9 : RSL, 2.5V, 2.5V

## 10. Generation

## 11. "—"

## 12. Package

M : μBGA® packages<sup>1)</sup> for Mirrored Package  
 N : μBGA® packages<sup>1)</sup> for Normal Package  
 S : μBGA® packages<sup>1)</sup> for Consumer Package  
 F : WBGA  
 G : WBGA Lead-Free  
 H : WBGA Lead-Free for So-RIMM Module  
 T : Consumer WBGA (54ball) & Lead-Free  
 R : Consumer WBGA (54ball)  
 D : FBGA & Lead-Free

## Notes

1) μBGA® packages are registered trademarks of Tessera.

## 13. Temp, Power

C : Commercial, Normal  
 L : Commercial, Low  
 I : Industrial, Normal

## 14~15. Speed (t<sub>CYCLE</sub>, t<sub>RAC</sub>, t<sub>RC</sub>)

DS : for Daisy chain Sample  
 N1 : 600MHz(1.667ns), -32, 32clks, for Long channel  
 T9 : 533MHz(1.85ns), -32P, 28clks, for Long channel  
 N9 : 533MHz(1.875ns), -32, 28clks, for Long channel  
 M9 : 533MHz(1.875ns), -35, 32clks, for Long channel  
 S9 : 533MHz(1.875ns), -35, 32clks, for Short channel  
  
 M8 : 400MHz(2.5ns), -40, 28clks, for Long channel  
 K8 : 400MHz(2.5ns), -45, 28clks, for Long channel  
 S8 : 400MHz(2.5ns), -45, 28clks, for Short channel  
  
 K7 : 356MHz(2.81ns), -45, 28clks, for Long channel  
 G6 : 300MHz(3.33ns), -53.3, 28clks, for Long channel  
 S6 : 300MHz(3.33ns), -53.3, 28clks, for Short channel

**K** **4** **R** X X X X X X X - X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 16. Packing “Packing Type Reference”

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other ( Tray, Tube, Jar )	0 ( Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

## 17~18. Customer “Customer List Reference”